

IN THE CLAIMS:

Please amend Claim 5 and add new Claims 13 and 14, as shown below.

1 to 4. (Cancelled)

5. (Currently Amended) An image pickup apparatus comprising:

a lead of a flexible wiring film;

an image pickup element chip electrically connected to the lead at an electrical connection point; and

a cover glass for protecting a surface of the image pickup element chip,

wherein the lead, the image pickup element chip, and the cover glass are sealed with a sealant in a peripheral portion of the image pickup element chip,

wherein the lead has a hole formed in a portion of the lead in contact with the sealant, with a part of the hole being positioned outside the cover glass,

wherein the sealant is applied so that sealant flows on the lead toward an end of the lead,

wherein the sealant flowing on the lead toward the end of the lead flows all the way to the end of the lead, and

wherein the portion of the lead being is disposed between the electrical connection point and an area outer end of the lead. ~~lead bonded to an insulating base film,~~

~~wherein a part of the hole is positioned outside the cover glass, and~~

~~wherein the lead has a thickness of not greater than 35 μ m.~~

6 and 7. (Cancelled)

8. (Previously Presented) The image pickup apparatus according to Claim 5, wherein at least one of a layer for preventing reflection of external light and a layer for preventing multiple reflection is formed between the lead and the cover glass.

9. (Previously Presented) An image pickup system comprising:
the image pickup apparatus according to Claim 5;
an optical system for focusing light on the image pickup apparatus; and
a signal processing circuit for processing an output signal from the image pickup apparatus.

10 and 11. (Cancelled)

12. (Previously Presented) The image pickup apparatus according to Claim 5, wherein the thickness of the lead is within the range of 18 μm to 35 μm .

13. (New) The image pickup apparatus according to Claim 5, wherein the portion of the lead is disposed between the electrical connection point and an area of the lead bonded to an insulating base film.

14. (New) The image pickup apparatus according to Claim 5, wherein the lead has a thickness of not greater than 35 μm .